506230248 09/01/2020

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHAO-JUNG CHEN	08/20/2020
YU-MIN LIN	08/20/2020
SHENG-TSAI WU	08/20/2020
SHIN-YI HUANG	08/20/2020
ANG-YING LIN	08/20/2020
TZU-HSUAN NI	08/20/2020
YUAN-YIN LO	08/21/2020

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17005310

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	094479-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	09/01/2020

PATENT 506230248 REEL: 053650 FRAME: 0321

Total Attachments: 2

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> PATENT REEL: 053650 FRAME: 0322

ASSIGNMENT

WHEREAS,

1.Chao-Jung Chen 3.Sheng-Tsai Wu 5.Ang-Ying Lin 7.Yuan-Yin Lo 2.Yu-Min Lin 4.Shin-Yi Huang 6.Tzu-Hsuan Ni

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: MULTI-CHIP PACKAGE AND MANUFACTURE METHOD THEREOF

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. Industrial Technology Research Institute

of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu
31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Chao-Jung Chen	_Date:			
Sole or First Joint Inventor: Chao-Jung Chen				
Signature: <u>u Miu Lin</u>	_Date:			
Second Joint Inventor (if any): Yu-Min Lin				
Signature: Sherfi-Tsai Wu	_Date: 7020 . J. 20			
Third Joint Inventor (if any): Sheng-Tsai Wu				
Signature: 5 hin - TT Hung	Date: 7070 (8.)U			
Fourth Joint Inventor (if any): Shin-Yi Huang				
Signature: Ang - King Lin	_Date:			
Fifth Joint Inventor (if any): Ang-Ying Lin				
Signature: 174 - Hsuan Ni	_Date: _১০১০ ন			
Sixth Joint Inventor (if any): Tzu-Hsuan Ni				
Signature: Yuan-Yin Lo	_Date:			
Seventh Joint Inventor (if any): Yuan-Yin Lo				